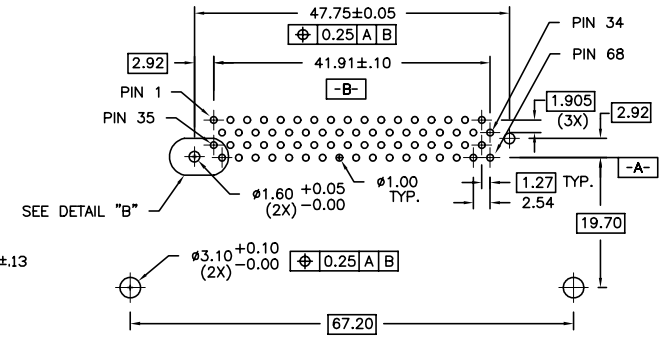
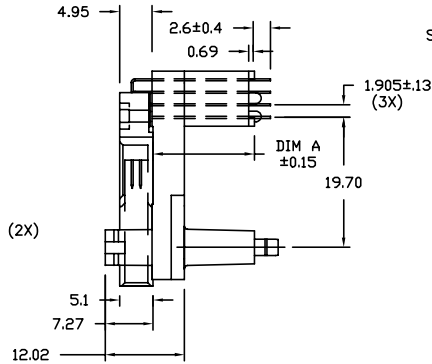
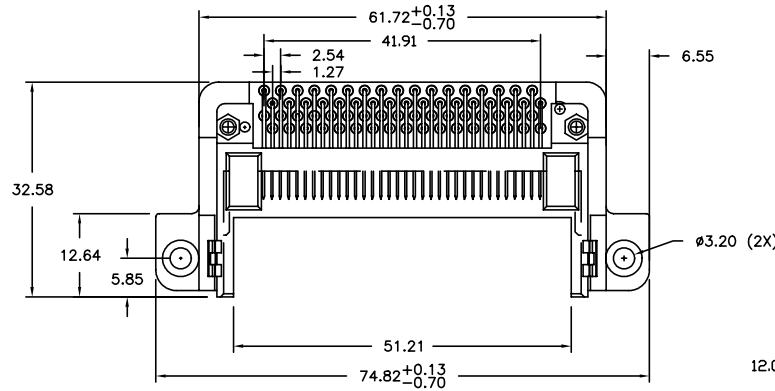
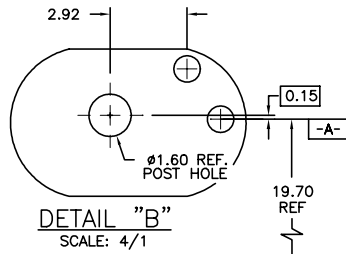
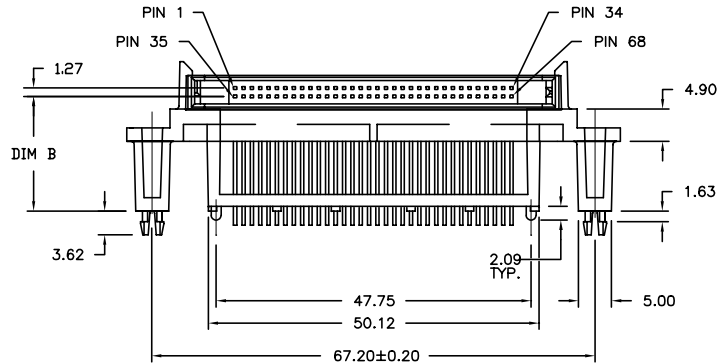


| | | |
|----------------|---------|---------|
| PRODUCT NO. | DIM "A" | DIM "B" |
| 10120633-001LF | 8.90 | 10.8 |



P.C.B. LAYOUT



NOTES:

- MATERIAL:
CONTACT - COPPER ALLOY
HOUSING: HIGH TEMPERATURE THERMOPLASTIC UL94-V0 BLACK
- PLATING:
CONTACT - ALL OVER 0.5um NICKEL UNDER PLATING
0.1um GOLD OVER 0.5um PALLADIUM
NICKEL SELECTIVE PLATING ON CONTACT.
2.5um PURE TIN PLATING ON LEAD FREE SOLDER TAIL
- MATING CONNECTOR
JEIDA/PCMCIA SPECIFICATION
- IF LEAD FREE P/N. THE HOUSING WILL WITHSTAND EXPOSURE TO 260°C PEAK TEMPERATURE FOR 10 SECONDS IN A WAVE SOLDER APPLICATION WITH A 1.00MM MINIMUM THICK CIRCUIT BOARD.
- IF LEAD FREE P/N. PACKAGING MEETS GS-14-920 SPECIFICATION
- LEAD FREE PRODUCT MEETS EUROPEAN UNION DIRECTIVES AND OTHER COUNTRY REGULATIONS AS DESCRIBED IN GS-22-008
- PRODUCT SPECIFICATION APR-12-031,
PACKING SPECIFICATION BUS-14-357

| | | | | | | |
|--------------|--------------|---|-----------|---------------------------------------|--------------------------------------|-------------------------------|
| mat'l. code | | surface ASME Y14.5 / tolerance ASME Y14.5 | | projection | product family PCMCIA | |
| ltr ecn nodr | | date | | tolerances unless otherwise specified | | title |
| A | - | ZK | 04/13/12 | angle 0°±2' | MM | HEADER ASSEMBLY W/STANDOFF |
| B | BLX-N-012546 | ZK | 06/15/12 | | | |
| | | | | 0.XXX±0.05 | | scale 1:1 |
| | | dr | ZK HU | 04/13/12 | dwg no 10120633 sheet 1 of 1 size A4 | |
| | | enr | ZK HU | 04/13/12 | FCI | |
| | | chr | RICK BIAN | 04/13/12 | type Product Customer Drawing | |
| | | appd | RICK BIAN | 04/13/12 | | |
| sheet index | revision | sheet 1 | | | | |